

Silicon Photonics Yole

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This book provides the first comprehensive, up-to-date and self-contained introduction to the emergent field of Programmable Integrated Photonics (PIP). It covers both theoretical and practical aspects, ranging from basic technologies and the building of photonic component blocks, to design alternatives and principles of complex programmable photonic circuits, their limiting factors, techniques for characterization and performance monitoring/control, and their salient applications both in the classical as well as in the quantum information fields. The book concentrates and focuses mainly on the distinctive features of programmable photonics, as compared to more traditional ASPIC approaches. After some years during which the Application Specific Photonic Integrated Circuit (ASPIC) paradigm completely dominated the field of integrated optics, there has been an increasing interest in PIP. The rising interest in PIP is justified by the surge in a number of emerging applications that call for true flexibility and reconfigurability, as well as low-cost, compact, and low-power consuming devices. Programmable Integrated Photonics is a new paradigm that aims at designing common integrated optical hardware configurations, which by suitable programming, can implement a variety of functionalities. These in turn can be exploited as basic operations in many application fields. Programmability enables, by means of external control signals, both chip reconfiguration for multifunction operation, as well as chip stabilization against non-ideal operations due to fluctuations in environmental conditions and fabrication errors. Programming also allows for the activation of parts of the chip, which are not essential for the implementation of a given functionality, but can be of help in reducing noise levels through the diversion of undesired reflections.

As silicon reaches its theoretical performance limits for power electronics, industry is shifting toward wide-bandgap materials like Gallium Nitride (GaN), whose properties provide clear benefits in power converters for consumer and industrial electronics. In over 150 pages covering the technology, its applications, markets and future potential, this book delves into GaN technology and its importance for power electronics professionals engaged with its implementation in power devices. The properties of GaN, such as low leakage current, significantly reduced power losses, higher power density and the ability to tolerate higher operating temperatures, all from a device smaller than its silicon-only equivalent, provide design advantages allowing previously unimaginable application performance. As an alternative to silicon, GaN can provide clear benefits in power converters for consumer and industrial electronics; chargers for wireless devices, including 5G; driver circuits for motor control; and power switches in automotive and space applications. The book also explores why GaN-based devices hold the key to addressing the energy efficiency agenda, a key strategic initiative in increasingly power-reliant industries such as data centers, electric vehicles, and renewable energy systems. Highly efficient residential and commercial energy storage systems using GaN technology will enable distribution, local storage, and on-demand access to renewable energy. Continued progress in the battery market will lead to declining battery costs and the development of smaller batteries that pair with GaN technology-based converters and inverters. Thermal management is critical in power electronics, and high efficiency in higher-power systems is always a focus. With GaN, a 50% reduction in losses can be achieved, reducing the costs and area required to manage heat. The book delves into GaN's electrical characteristics and how these can be exploited in power devices. There are also chapters that cross into the key applications for GaN devices for several markets such as space, automotive, audio, motor control and data centers. Each chapter provides a comprehensive overview of the subject matter for anyone who wants to stay on the leading edge of power electronics. Silicon photonics uses chip-making techniques to fabricate photonic circuits. The emerging

technology is coming to market at a time of momentous change. The need of the Internet content providers to keep scaling their data centers is becoming increasingly challenging, the chip industry is facing a future without Moore's law, while telcos must contend with a looming capacity crunch due to continual traffic growth. Each of these developments is significant in its own right. Collectively, they require new thinking in the design of chips, optical components, and systems. Such change also signals new business opportunities and disruption.

Notwithstanding challenges, silicon photonics' emergence is timely because it is the future of several industries. For the optical industry, the technology will allow designs to be tackled in new ways. For the chip industry, silicon photonics will become the way of scaling post-Moore's law. New system architectures enabled by silicon photonics will improve large-scale computing and optical communications. *Silicon Photonics: Fueling the Next Information Revolution* outlines the history and status of silicon photonics. The book discusses the trends driving the datacom and telecom industries, the main but not the only markets for silicon photonics. In particular, developments in optical transport and the data center are discussed as are the challenges. The book details the many roles silicon photonics will play, from wide area networks down to the chip level. Silicon photonics is set to change the optical components and chip industries; this book explains how. Captures the latest research assessing silicon photonics development and prospects Demonstrates how silicon photonics addresses the challenges of managing bandwidth over distance and within systems Explores potential applications of SiP, including servers, datacenters, and Internet of Things

This book gives a fascinating picture of the state-of-the-art in silicon photonics and a perspective on what can be expected in the near future. It is composed of a selected number of reviews authored by world leaders in the field and is written from both academic and industrial viewpoints. An in-depth discussion of the route towards fully integrated silicon photonics is presented. This book will be useful not only to physicists, chemists, materials scientists, and engineers but also to graduate students who are interested in the fields of microphotonics and optoelectronics.

Contributed articles on art and technology.

This book sets out to build bridges between the domains of photonic device physics and neural networks, providing a comprehensive overview of the emerging field of "neuromorphic photonics." It includes a thorough discussion of evolution of neuromorphic photonics from the advent of fiber-optic neurons to today's state-of-the-art integrated laser neurons, which are a current focus of international research. *Neuromorphic Photonics* explores candidate interconnection architectures and devices for integrated neuromorphic networks, along with key functionality such as learning. It is written at a level accessible to graduate students, while also intending to serve as a comprehensive reference for experts in the field.

This book provides a detailed overview of the most recent advances in the fascinating world of light-emitting diodes (LEDs), organic light-emitting diodes (OLEDs), and photodetectors (PDs). Chapters in Section 1 discuss the different types and designs of LEDs/OLEDs and their use in light output, color rendering, and more. Chapters in Section 2 examine innovative structures, emerging materials, and physical effects of PDs. This book is a useful resource for students and scientists working in the field of photonics and advanced technologies.

Silicon photonics has evolved rapidly as a research topic with enormous application potential. The high refractive index contrast of silicon-on-insulator (SOI) shows great promise for submicron waveguide structures suited for integration on the chip scale in the near-infrared region. Ge- and GeSn-Si heterostructures with different elastic strain levels already provide expansion of the spectral range, high-speed operation, efficient modulation and switching of optical signals, and enhanced light emission and lasing. This book focuses on the integration of heterostructure devices with silicon photonics. The authors have attempted to merge a concise treatment of classical silicon photonics with a description of principles, prospects,

challenges, and technical solution paths of adding silicon-based heterostructures. The book discusses the basics of heterostructure-based silicon photonics, system layouts, and key device components, keeping in mind the application background. Special focus is placed on SOI-based waveguide configurations and Ge- and GeSn-Si heterostructure devices for light detection, modulation, and light emission and lasing. The book also provides an overview of the technological and materials science challenges connected with integration on silicon. The first half of the book is mainly for readers who are interested in the topic because of its increasing importance in different fields, while the latter half covers different device structures for light emission, detection, modulation, extension of the wavelength beyond 1.6 μm , and lasing, as well as future challenges.

This book starts with background concerning three-dimensional integration - including their low energy consumption and high speed image processing - and then proceeds to how to construct them and which materials to use in particular situations. The book covers numerous applications, including next generation smart phones, driving assistance systems, capsule endoscopes, homing missiles, and many others. The book concludes with recent progress and developments in three dimensional packaging, as well as future prospects.

Advanced Characterization of Nanostructured Materials — Probing the Structure and Dynamics with Synchrotron X-Rays and Neutrons is a collection of chapters which review the characterization of the structure and internal dynamics of a wide variety of nanostructured materials using various synchrotron X-ray and neutron scattering techniques. It is intended for graduate students and researchers who might be interested in learning about and applying these methods. The authors are well-known practitioners in their fields of research who provide detailed and authoritative accounts of how these techniques have been applied to study systems ranging from thin films and monolayers on solid surfaces and at liquid-air, liquid-liquid and solid-liquid interfaces; nanostructured composite materials; battery materials, and catalytic materials. While there have been a great many books published on nanoscience, there are relatively few that have discussed in one volume detailed synchrotron X-ray and neutron methods for advanced characterization of nanomaterials in thin films, composite materials, catalytic and battery materials and at interfaces. This book should provide an incentive and a reference for researchers in nanomaterials for using these techniques as a powerful way to characterize their samples. It should also help to popularize the use of synchrotron and neutron facilities by the nanoscience community.

The AlInGaN and ZnO materials systems have proven to be one of the scientifically and technologically important areas of development over the past 15 years, with applications in UV/visible optoelectronics and in high-power/high-frequency microwave devices. The pace of advances in these areas has been remarkable and the wide band gap community relies on books like the one we are proposing to provide a review and summary of recent progress. Recent advancements in generation of intense X-ray laser ultrashort pulses open opportunities for particle acceleration in solid-state plasmas. Wakefield acceleration in crystals or carbon nanotubes shows promise of unmatched ultra-high accelerating gradients and possibility to shape the future of high energy physics colliders. This book summarizes the discussions of the 'Workshop on Beam Acceleration in Crystals and Nanostructures' (Fermilab, June 24-25 , 2019), presents next steps in theory and modeling and outlines major physics and technology challenges toward proof-of-principle demonstration experiments.

The successful launch of viable MEMs product hinges on MEMS reliability, the reliability and qualification for MEMs based products is not widely understood. Companies that have a deep understanding of MEMs reliability view the information as a competitive advantage and are reluctant to share it. *MEMs Reliability*, focuses on the reliability and manufacturability of MEMS at a fundamental level by addressing process development and characterization, material property characterization, failure mechanisms and physics of failure (POF), design strategies

for improving yield, design for reliability (DFR), packaging and testing.

High Mobility Materials for CMOS Applications provides a comprehensive overview of recent developments in the field of (Si)Ge and III-V materials and their integration on Si. The book covers material growth and integration on Si, going all the way from device to circuit design. While the book's focus is on digital applications, a number of chapters also address the use of III-V for RF and analog applications, and in optoelectronics. With CMOS technology moving to the 10nm node and beyond, however, severe concerns with power dissipation and performance are arising, hence the need for this timely work on the advantages and challenges of the technology. Addresses each of the challenges of utilizing high mobility materials for CMOS applications, presenting possible solutions and the latest innovations. Covers the latest advances in research on heterogeneous integration, gate stack, device design and scalability. Provides a broad overview of the topic, from materials integration to circuits.

This book offers a unified presentation of metamaterials building from fundamental nanophotonic principles.

Reliability of Semiconductor Lasers and Optoelectronic Devices simplifies complex concepts of optoelectronics reliability with approachable introductory chapters and a focus on real-world applications. This book provides a brief look at the fundamentals of laser diodes, introduces reliability qualification, and then presents real-world case studies discussing the principles of reliability and what occurs when these rules are broken. Then this book comprehensively looks at optoelectronics devices and the defects that cause premature failure in them and how to control those defects. Key materials and devices are reviewed including silicon photonics, vertical-cavity surface-emitting lasers (VCSELs), InGaN LEDs and lasers, and AlGaIn LEDs, covering the majority of optoelectronic devices that we use in our everyday lives, powering the Internet, telecommunication, solid-state lighting, illuminators, and many other applications. This book features contributions from experts in industry and academia working in these areas and includes numerous practical examples and case studies. This book is suitable for new entrants to the field of optoelectronics working in R&D. • Includes case studies and numerous examples showing best practices and common mistakes affecting optoelectronics reliability written by experts working in the industry • Features the first wide-ranging and comprehensive overview of fiber optics reliability engineering, covering all elements of the practice from building a reliability laboratory, qualifying new products, to improving reliability on mature products. • Provides a look at the reliability issues and failure mechanisms for silicon photonics, VCSELs, InGaN LEDs and lasers, AlGaIn LEDs, and more.

MEMS sensors and actuators are enabling components for smartphones, AR/VR, and wearable electronics. MEMS packaging is recognized as one of the most critical activities to design and manufacture reliable MEMS. A unique challenge to MEMS packaging is how to protect moving MEMS devices during manufacturing and operation. With the introduction of wafer level capping and encapsulation processes, this barrier is removed successfully. In addition, MEMS devices should be integrated with their electronic chips with the smallest footprint possible. As a result, 3D packaging is applied to connect the devices vertically for the most effective integration. Such 3D packaging also paves the way for further heterogeneous integration of MEMS devices, electronics, and other functional devices. This book consists of chapters written by leaders developing products in a MEMS industrial setting and faculty members conducting research in an academic setting. After an introduction chapter, the practical issues are covered: through-silicon vias (TSVs), vertical interconnects, wafer level packaging, motion sensor-to-CMOS bonding, and use of printed circuit board technology to fabricate MEMS. These chapters are written by leaders developing MEMS products. Then, fundamental issues are discussed, topics including encapsulation of MEMS, heterogeneous integration, microfluidics, solder bonding, localized sealing, microsprings, and reliability.

Contents: Introduction to MEMS Packaging (Y C Lee, Ramesh Ramadoss and Nils Hoivik)Silex's TSV Technology: Overview of Processes and MEMS Applications (Tomas Bauer and Thorbjörn Ebefors)Vertical Interconnects for High-end MEMS (Maaïke M Visser Taklo and Sigurd Moe)Using Wafer-Level Packaging to Improve Sensor Manufacturability and Cost (Paul Pickering, Collin Twanow and Dean Spicer)Nasiri Fabrication Process for Low-Cost Motion Sensors in the Consumer Market (Steven Nasiri, Ramesh Ramadoss and Sandra Winkler)PCB Based MEMS and Microfluidics (Ramesh Ramadoss, Antonio Luque and Carmen Aracil)Single Wafer Encapsulation of MEMS Resonators (Janna Rodriguez and Thomas Kenny)Heterogeneous Integration and Wafer-Level Packaging of MEMS (Masayoshi Esashi and Shuji Tanaka)Packaging of Membrane-Based Polymer Microfluidic Systems (Yu-Chuan Su)Wafer-Level Solder Bonding by Using Localized Induction Heating (Hsueh-An Yang, Chiung-Wen Lin and Weileun Fang)Localized Sealing Schemes for MEMS Packaging (Y T Cheng, Y C Su and Liwei Lin)Microsprings for High-Density Flip-Chip Packaging (Eugene M Chow and Christopher L Chua)MEMS Reliability (Chien-Ming Huang, Arvind Sai SarathiVasan, Yunhan Huang, Ravi Doraiswami, Michael Osterman and Michael Pecht) Readership: Researchers and graduate students participating in research, R&D, and manufacturing of MEMS products; professionals associated with the integration for systems represented by smartphones, AR/VR, and wearable electronics. Keywords:

MEMS;Packaging;Microelectromechanical

Systems;Reliability;Microstructures;Sensors;ActuatorsReview: Key Features: The book covers engineering topics critical to product development as well as research topics critical to integration for future MEMS-enabled systemsIt is a major resource for those participating in MEMS and for every professional associated with the integration for systems represented by smartphones, AR/VR and wearable electronics

Mid-infrared Optoelectronics: Materials, Devices, and Applications addresses the new materials, devices and applications that have emerged over the last decade, along with exciting areas of research. Sections cover fundamentals, light sources, photodetectors, new approaches, and the application of mid-IR devices, with sections discussing LEDs, laser diodes, and quantum cascade lasers, mid-infrared optoelectronics, emerging research areas, dilute bismide and nitride alloys, Group-IV materials, gallium nitride heterostructures, and new nonlinear materials. Finally, the most relevant applications of mid-infrared devices are reviewed in industry, gas sensing, spectroscopy, and imaging. This book presents a key reference for materials scientists, engineers and professionals working in R&D in the area of semiconductors and optoelectronics. Provides a comprehensive overview of mid-infrared photodetectors and light sources and the latest materials and devices Reviews emerging areas of research in the field of mid-infrared optoelectronics, including new materials, such as wide bandgap materials, chalcogenides and new approaches, like heterogeneous integration Includes information on the most relevant applications in industry, like gas sensing, spectroscopy and imaging

The development of integrated silicon photonic circuits has recently been driven by the Internet and the push for high bandwidth as well as the need to reduce power dissipation induced by high data-rate signal transmission. To reach these goals, efficient passive and active silicon photonic devices, including waveguide, modulators, photodetectors,

This book discusses some research results for CMOS-compatible silicon-based optical devices and interconnections. With accurate simulation and experimental demonstration, it provides insights on silicon-based modulation, advanced multiplexing, polarization and efficient coupling controlling technologies, which are widely used in silicon photonics. Researchers, scientists, engineers and especially students in the field of silicon photonics can benefit from the book. This book provides valuable knowledge, useful methods and practical design that can be considered in emerging silicon-based optical interconnections and communications. And it also

give some guidance to student how to organize and complete an good dissertation.

Silicon photonics is beginning to play an important role in driving innovations in communication and computation for an increasing number of applications, from health care and biomedical sensors to autonomous driving, datacenter networking, and security. In recent years, there has been a significant amount of effort in industry and academia to innovate, design, develop, analyze, optimize, and fabricate systems employing silicon photonics, shaping the future of not only Datacom and telecom technology but also high-performance computing and emerging computing paradigms, such as optical computing and artificial intelligence. Different from existing books in this area, *Silicon Photonics for High-Performance Computing and Beyond* presents a comprehensive overview of the current state-of-the-art technology and research achievements in applying silicon photonics for communication and computation. It focuses on various design, development, and integration challenges, reviews the latest advances spanning materials, devices, circuits, systems, and applications. Technical topics discussed in the book include:

- Requirements and the latest advances in high-performance computing systems
- Device- and system-level challenges and latest improvements to deploy silicon photonics in computing systems
- Novel design solutions and design automation techniques for silicon photonic integrated circuits
- Novel materials, devices, and photonic integrated circuits on silicon
- Emerging computing technologies and applications based on silicon photonics

Silicon Photonics for High-Performance Computing and Beyond presents a compilation of 19 outstanding contributions from academic and industry pioneers in the field. The selected contributions present insightful discussions and innovative approaches to understand current and future bottlenecks in high-performance computing systems and traditional computing platforms, and the promise of silicon photonics to address those challenges. It is ideal for researchers and engineers working in the photonics, electrical, and computer engineering industries as well as academic researchers and graduate students (M.S. and Ph.D.) in computer science and engineering, electronic and electrical engineering, applied physics, photonics, and optics.

The chips in present-day cell phones already contain billions of sub-100-nanometer transistors. By 2020, however, we will see systems-on-chips with trillions of 10-nanometer transistors. But this will be the end of the miniaturization, because yet smaller transistors, containing just a few control atoms, are subject to statistical fluctuations and thus no longer useful. We also need to worry about a potential energy crisis, because in less than five years from now, with current chip technology, the internet alone would consume the total global electrical power! This book presents a new, sustainable roadmap towards ultra-low-energy (femto-Joule), high-performance electronics. The focus is on the energy-efficiency of the various chip functions: sensing, processing, and communication, in a top-down spirit involving new architectures such as silicon brains, ultra-low-voltage circuits, energy harvesting, and 3D silicon technologies. Recognized world leaders from industry and from the research community share their views of this nanoelectronics future. They discuss, among other things, ubiquitous communication based on mobile companions, health and care supported by autonomous implants and by personal carebots, safe and efficient mobility assisted by co-pilots equipped with intelligent micro-electromechanical systems, and internet-based education for a billion people from kindergarden to retirement. This book should help and interest all those who will have to make decisions associated with future electronics: students, graduates, educators, and researchers, as well as managers, investors, and policy makers.

Introduction: Towards Sustainable 2020 Nanoelectronics.- From Microelectronics to Nanoelectronics.- The Future of Eight Chip Technologies.- Analog-Digital Interfaces.- Interconnects and Transceivers.- Requirements and Markets for Nanoelectronics.- ITRS: The International Technology Roadmap for Semiconductors.- Nanolithography.- Power-Efficient Design Challenges.- Superprocessors and Supercomputers.- Towards Terabit Memories.- 3D Integration for Wireless Multimedia.- The

Next-Generation Mobile User-Experience.- MEMS (Micro-Electro-Mechanical Systems) for Automotive and Consumer.- Vision Sensors and Cameras.- Digital Neural Networks for New Media.- Retinal Implants for Blind Patients.- Silicon Brains.- Energy Harvesting and Chip Autonomy.- The Energy Crisis.- The Extreme-Technology Industry.- Education and Research for the Age of Nanoelectronics.- 2020 World with Chips.

This comprehensive handbook serves as a professional reference as well as a practitioner's guide to today's most complete and concise view of nanoscale networking and communications. It offers in-depth coverage of theory, technology, and practice as they relate to established technologies and recent advancements. It explores practical solutions to a wide range of nanoscale networking and communications issues. Individual chapters, authored by leading experts in the field, address the immediate and long-term challenges in the authors' respective areas of expertise.

Significant progress has been made in advanced packaging in recent years. Several new packaging techniques have been developed and new packaging materials have been introduced. This book provides a comprehensive overview of the recent developments in this industry, particularly in the areas of microelectronics, optoelectronics, digital health, and bio-medical applications. The book discusses established techniques, as well as emerging technologies, in order to provide readers with the most up-to-date developments in advanced packaging.

Edited by key figures in 3D integration and written by top authors from high-tech companies and renowned research institutions, this book covers the intricate details of 3D process technology. As such, the main focus is on silicon via formation, bonding and debonding, thinning, via reveal and backside processing, both from a technological and a materials science perspective. The last part of the book is concerned with assessing and enhancing the reliability of the 3D integrated devices, which is a prerequisite for the large-scale implementation of this emerging technology. Invaluable reading for materials scientists, semiconductor physicists, and those working in the semiconductor industry, as well as IT and electrical engineers.

Compiles current research into the analysis and design of power electronic converters for industrial applications and renewable energy systems, presenting modern and future applications of power electronics systems in the field of electrical vehicles. With emphasis on the importance and long-term viability of Power Electronics for Renewable Energy this book brings together the state of the art knowledge and cutting-edge techniques in various stages of research. The topics included are not currently available for practicing professionals and aim to enable the reader to directly apply the knowledge gained to their designs. The book addresses the practical issues of current and future electric and plug-in hybrid electric vehicles (PHEVs), and focuses primarily on power electronics and motor drives based solutions for electric vehicle (EV) technologies. Propulsion system requirements and motor sizing for EVs is discussed, along with practical system sizing examples. Key EV battery technologies are explained as well as corresponding battery management issues. PHEV power system architectures and advanced power electronics intensive charging infrastructures for EVs and PHEVs are detailed.

EV/PHEV interface with renewable energy is described, with practical examples.

This book explores new topics for further research needed world-wide, and defines existing challenges, concerns, and selected problems that comply with international trends, standards, and programs for electric power conversion, distribution, and sustainable energy development. It will lead to the advancement of the current state-of-

the art applications of power electronics for renewable energy, transportation, and industrial applications and will help add experience in the various industries and academia about the energy conversion technology and distributed energy sources. Combines state of the art global expertise to present the latest research on power electronics and its application in transportation, renewable energy and different industrial applications. Offers an overview of existing technology and future trends, with discussion and analysis of different types of converters and control techniques (power converters, high performance power devices, power system, high performance control system and novel applications). Systematic explanation to provide researchers with enough background and understanding to go deeper in the topics covered in the book. This book is volume III of a series of books on silicon photonics. It reports on the development of fully integrated systems where many different photonics component are integrated together to build complex circuits. This is the demonstration of the fully potentiality of silicon photonics. It contains a number of chapters written by engineers and scientists of the main companies, research centers and universities active in the field. It can be of use for all those persons interested to know the potentialities and the recent applications of silicon photonics both in microelectronics, telecommunication and consumer electronics market.

This book is a collection of five original research articles on silicon photonics. The discussed issues are organized into two parts. Part 1 describes the science behind the silicon photonics emphasizing the role of photonic circuits on silicon, and Part 2 describes applications in waveguide and optical transmissions. This book should be of interest to academic researchers and engineers. The chapters included are fundamental science and applications of silicon photonics, optical properties of thin nanocrystalline silicon films, microporous silicon in gas sensing, Mach-Zehnder interferometer cell-based silicon waveguide, experimental study of porous silicon films, and integrated optical switches and their applications.

The main objective of this book is to provide the necessary background to work with big data by introducing some novel optimization algorithms and codes capable of working in the big data setting as well as introducing some applications in big data optimization for both academics and practitioners interested, and to benefit society, industry, academia, and government. Presenting applications in a variety of industries, this book will be useful for the researchers aiming to analyse large scale data. Several optimization algorithms for big data including convergent parallel algorithms, limited memory bundle algorithm, diagonal bundle method, convergent parallel algorithms, network analytics, and many more have been explored in this book.

Silicon photonics is currently a very active and progressive area of research, as silicon optical circuits have emerged as the replacement technology for copper-based circuits in communication and broadband networks. The demand for ever improving communications and computing performance continues, and this in turn means that photonic circuits are finding ever increasing application areas. This text provides an important and timely overview of the 'hot topics' in the field, covering the various aspects of the technology that form the research area of silicon photonics. With contributions from some of the world's leading researchers in silicon photonics, this book collates the latest advances in the technology. Silicon Photonics: the State of the Art opens with a highly informative foreword, and continues to feature: the integrated

photonic circuit; silicon photonic waveguides; photonic bandgap waveguides; mechanisms for optical modulation in silicon; silicon based light sources; optical detection technologies for silicon photonics; passive silicon photonic devices; photonic and electronic integration approaches; applications in communications and sensors. Silicon Photonics: the State of the Art covers the essential elements of the entire field that is silicon photonics and is therefore an invaluable text for photonics engineers and professionals working in the fields of optical networks, optical communications, and semiconductor electronics. It is also an informative reference for graduate students studying for PhD in fibre optics, integrated optics, optical networking, microelectronics, or telecommunications.

Nanoelectronics: Devices, Circuits and Systems explores current and emerging trends in the field of nanoelectronics, from both a devices-to-circuits and circuits-to-systems perspective. It covers a wide spectrum and detailed discussion on the field of nanoelectronic devices, circuits and systems. This book presents an in-depth analysis and description of electron transport phenomenon at nanoscale dimensions. Both qualitative and analytical approaches are taken to explore the devices, circuit functionalities and their system applications at deep submicron and nanoscale levels. Recent devices, including FinFET, Tunnel FET, and emerging materials, including graphene, and its applications are discussed. In addition, a chapter on advanced VLSI interconnects gives clear insight to the importance of these nano-transmission lines in determining the overall IC performance. The importance of integration of optics with electronics is elucidated in the optoelectronics and photonic integrated circuit sections of this book. This book provides valuable resource materials for scientists and electrical engineers who want to learn more about nanoscale electronic materials and how they are used. Shows how electronic transport works at the nanoscale level Demonstrates how nanotechnology can help engineers create more effective circuits and systems Assesses the most commonly used nanoelectronic devices, explaining which is best for different situations

This book describes for readers various technical outcomes from the EU-project IoSense. The authors discuss sensor integration, including LEDs, dust sensors, LIDAR for automotive driving and 8 more, demonstrating their use in simulations for the design and fabrication of sensor systems. Readers will benefit from the coverage of topics such as sensor technologies for both discrete and integrated innovative sensor devices, suitable for high volume production, electrical, mechanical, security and software resources for integration of sensor system components into IoT systems and IoT-enabling systems, and IoT sensor system reliability. Describes from component to system level simulation, how to use the available simulation techniques for reaching a proper design with good performance; Explains how to use simulation techniques such as Finite Elements, Multi-body, Dynamic, stochastics and many more in the virtual design of sensor systems; Demonstrates the integration of several sensor solutions (thermal, dust, occupancy, distance, awareness and more) into large-scale system solutions in several industrial domains (Lighting, automotive, transport and more); Includes state-of-the-art simulation techniques, both multi-scale and multi-physics, for use in the electronic industry.

Silicon (Si) technologies provide an excellent platform for the design of microsystems where photonic and microelectronic functionalities are monolithically integrated on the same substrate. In recent years, a variety of passive and active Si photonic devices have been developed, and among them, photodetectors have attracted particular interest from the scientific community. Si photodiodes are typically designed to operate at visible wavelengths,

but, unfortunately, their employment in the infrared (IR) range is limited due to the neglectable Si absorption over 1100 nm, even though the use of germanium (Ge) grown on Si has historically allowed operations to be extended up to 1550 nm. In recent years, significant progress has been achieved both by improving the performance of Si-based photodetectors in the visible range and by extending their operation to infrared wavelengths. Near-infrared (NIR) SiGe photodetectors have been demonstrated to have a “zero change” CMOS process flow, while the investigation of new effects and structures has shown that an all-Si approach could be a viable option to construct devices comparable with Ge technology. In addition, the capability to integrate new emerging 2D and 3D materials with Si, together with the capability of manufacturing devices at the nanometric scale, has led to the development of new device families with unexpected performance. Accordingly, this Special Issue of Micromachines seeks to showcase research papers, short communications, and review articles that show the most recent advances in the field of silicon photodetectors and their respective applications.

This book is meant as an introduction to graphene plasmonics and aims at the advanced undergraduate and graduate students entering the field of plasmonics in graphene. In it different theoretical methods are introduced, starting with an elementary description of graphene plasmonics and evolving towards more advanced topics. This book is essentially self-contained and brings together a number of different topics about the field that are scattered in the vast literature. The text is composed of eleven chapters and of a set of detailed

appendices. It can be read in two different ways: Reading only the chapters to get acquainted

with the field of plasmonics in graphene or reading the chapters and studying the appendices

to get a working knowledge of the topic. The study of the material in this book will bring the

students to the forefront of the research in this field. Errata(s) Errata (159 KB) Contents:

Introduction Electromagnetic Properties of Solids in a Nutshell Surface Plasmon–Polaritons at

Dielectric–Metal Interfaces Graphene Surface Plasmons Excitation of Graphene Surface

Plasmons Launching Plasmons Using a Metallic Antenna Plasmonics in Periodic Arrays of

Graphene Ribbons Plasmons in Graphene Nanostructures and in One-dimensional

Channels Excitation of Surface Plasmon–Polaritons Using Dielectric Gratings Excitation of

Plasmons by an Emitting Dipole Concluding Remarks Readership: Advanced undergraduate

and graduate students entering the field of graphene plasmonics.

Explore core concepts, theories and formulations of phase-only Fresnel holograms, which paves the way for 3-D holographic display system.

This book aims to present fundamental aspects of optical communication techniques and advanced modulation techniques and extensive applications of optical communications systems and networks employing single-mode optical fibers as the transmission system. New digital techniques such as chromatic dispersion, polarization mode dispersion, nonlinear phase distortion effects, etc. will be discussed. Practical models for practice and understanding the behavior and dynamics of the devices and systems will be included.

This book presents the first comprehensive overview of the properties and fabrication methods of GaN-based power transistors, with contributions from the most active research groups in the field. It describes how gallium nitride has emerged as an excellent material for the fabrication of power transistors; thanks to the high energy gap, high breakdown field, and saturation velocity of GaN, these devices can reach breakdown voltages beyond the kV range, and very high switching frequencies, thus being suitable for application in power conversion systems.

Based on GaN, switching-mode power converters with efficiency in excess of 99 % have been already demonstrated, thus clearing the way for massive adoption of GaN transistors in the power conversion market. This is expected to have important advantages at both the environmental and economic level, since power conversion losses account for 10 % of global electricity consumption. The first part of the book describes the properties and advantages of gallium nitride compared to conventional semiconductor materials. The second part of the book

describes the techniques used for device fabrication, and the methods for GaN-on-Silicon mass production. Specific attention is paid to the three most advanced device structures: lateral transistors, vertical power devices, and nanowire-based HEMTs. Other relevant topics covered by the book are the strategies for normally-off operation, and the problems related to device reliability. The last chapter reviews the switching characteristics of GaN HEMTs based on a systems level approach. This book is a unique reference for people working in the materials, device and power electronics fields; it provides interdisciplinary information on material growth, device fabrication, reliability issues and circuit-level switching investigation. The growing demand for instant and reliable communication means that photonic circuits are increasingly finding applications in optical communications systems. One of the prime candidates to provide satisfactory performance at low cost in the photonic circuit is silicon. Whilst silicon photonics is less well developed as compared to some other material technologies, it is poised to make a serious impact on the telecommunications industry, as well as in many other applications, as other technologies fail to meet the yield/performance/cost trade-offs. Following a sympathetic tutorial approach, this first book on silicon photonics provides a comprehensive overview of the technology. Silicon Photonics explains the concepts of the technology, taking the reader through the introductory principles, on to more complex building blocks of the optical circuit. Starting with the basics of waveguides and the properties peculiar to silicon, the book also features: Key design issues in optical circuits. Experimental methods. Evaluation techniques. Operation of waveguide based devices. Fabrication of silicon waveguide circuits. Evaluation of silicon photonic systems. Numerous worked examples, models and case studies. Silicon Photonics is an essential tool for photonics engineers and young professionals working in the optical network, optical communications and semiconductor industries. This book is also an invaluable reference and a potential main text to senior undergraduates and postgraduate students studying fibre optics, integrated optics, or optical network technology.

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